

Notice of References Cited	Application/Control No. 10/694,649		Applicant(s)/Patent Under Reexamination BLAKE ET AL.	
	Examiner John C Hanley		Art Unit 2856	Page 1 of 1

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NON-PATENT DOCUMENTS

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	W	Mahesh C. Bhardwaj et al; "Non-Contact Ultrasound: The Last Frontier in Non-Destructive Testing and Evaluation"; Preprint of a chapter in Encyclopedia of Smart Materials, edited by Mel Schwartz, John Wiley & Sons; March 2002.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.